262, 144WORDS × 4BITS MULTIPORT DRAM

PRELIMINARY

DESCRIPTION

The TC524256BJ/BZ is a CMOS multiport memory equipped with a 262,144-words by 4-bits dynamic random access memory (RAM) port and a 512-words by 4-bits static serial access memory (SAM) port. The TC524256BJ/BZ supports three types of operations: random access to and from the RAM port, high speed serial access to and from the SAM port and bidirectional transfer of data between any selected row in the RAM port and the SAM port. The RAM port and the SAM port can be accessed independently except when data is being transferred between them internally. The TC524256BJ/BZ is fabricated using Toshiba's CMOS silicon gate process as well as advanced circuit designs to provide low power dissipation and wide operating margins.

FEATURES

1775.4		TC524256BJ/B		
	ITEM	- 80	- 10	
IRAC	RAS Access Time (Max.)	80ns	100ns	
	CAS Access Time (Max.)	25ns	25ns	
tAA	Column Address Access Time (Max.)	45ns	50ns	
tec	Cycle Time (Min.)	150ns	180ns	
tpc	Page Mode Cycle Time (Min.)	50ns	55ns	
tsca	Serial Access Time (Max.)	25ns	25ns	
tscc	Serial Cycle time (Min.)	30ns	30ns	
lcc1	RAM Operating Current	85mA	70mA	
	(SAM : Standby)			
Icc2A	SAM Operating Current	50mA	50mA	
	(RAM : Standby)			
ICC2	Standby Current	10mA	10mA	

- Single power supply of 5V±10% with a built-in
- VBB generator
 All inputs and outputs: TTL Compatible

Organization RAM Port

RAM Port : 262,144words×4bits SAM Port : 512words×4bits

RAM Port
 Fast Page Mode, Read - Modify - Write
 CAS before RAS Refresh, Hidden Refresh
 RAS only Refresh, Write per Bit
 512 refresh cycles/8ms

SAM Port
 High Speed Serial Read/Write Capability
 512 Tap Locations
 Fully Static Register

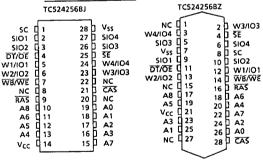
Fully Static Register
RAM · SAM Bidirectional Transfer
Read / Write / Pseudo Write Transfer
Real Time Read Transfer

Package TC524256BJ: SOJ28-P-400 TC524256BZ: ZIP28-P-400

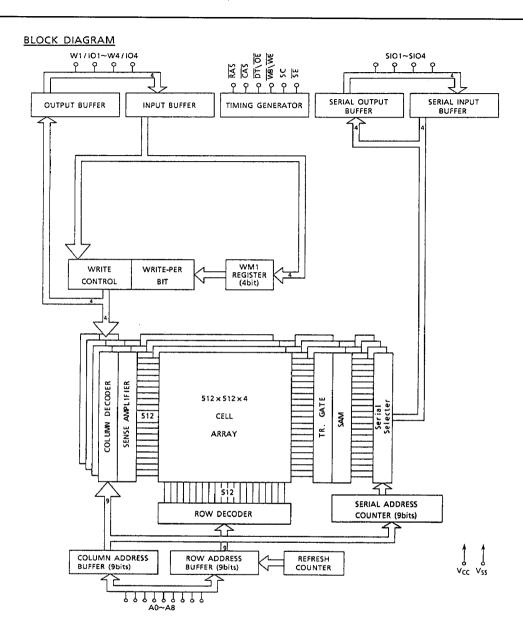
PIN NAME

A0~A8	Address inputs
RAS	Row Address Strobe
CAS	Column Address Strobe
DT / OE	Data Transfer / Output Enable
WB/WE	Write per Bit/Write Enable
W1/IO1~W4/IO4	Write Mask/Data IN, OUT
sc	Serial Clock
SE	Serial Enable
SIQ1~SIQ4	Serial Input / Output
V _{CC} / V _{SS}	Power (5V) / Ground
N. C.	No Connection

PIN CONNECTION



28Pin 400mil SOJ JEDEC Standard 28Pin 400mil height ZIP JEDEC Standard



ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT	NOTE
Vin. Vout	Input Output Voltage	- 1.0~7.0	٧	1
Vcc	Power Supply Voltage	- 1.0~7.0	V	1
T _{OPR}	Operating Temperature	0~70	•c	1
TSTG	Storage Temperature	- 55~150	°C	11
T _{SOLDER}	Soldering Temperature · Time	260-10	°C-sec	1
PD	Power Dissipation	1	w	11
Ιουτ	Short Circuit Output Current	50	mA	11

RECOMMENDED D.C. OPERATING CONDITIONS ($Ta = 0 \sim 70$ °C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT	NOTE
Vcc	Power Supply Voltage	4.5	5.0	5.5	V	2
VIH	Input High Voltage	2.4	_	6.5	V	2
VIL	Input Low Voltage	- 1.0	-	0.8	٧	2

CAPACITANCE ($V_{CC} = 5V$, f = 1MHz, $Ta = 25^{\circ}C$)

PARAMETER	MIN.	MAX.	UNIT
Input Capacitance	-	7	ρF
Input/Output Capacitance	-	9	
	Input Capacitance	Input Capacitance –	Input Capacitance – 7

Note: This parameter is periodically sampled and is not 100% tested.



D.C. ELECTRICAL CHARACTERISTICS $(V_{CC} = 5V \pm 10\%, Ta = 0 \sim 70^{\circ}C)$

TTAA (GAAA 000T)			TC52425	681/8Z-80	TC52425	681/82-10]	
ITEM (RAM PORT)	SAM PORT	SYMBOL	MIN.	MAX.	MIN.	MAX.	UNIT	NOTE
OPERATING CURRENT	Standby	1cc1		85		70		3, 4
$\begin{pmatrix} \text{RAS, CAS Cycling} \\ \text{t}_{\text{RC}} = \text{t}_{\text{RC}} \text{ min.} \end{pmatrix}$	Active	I _{CC1A}	_	125	-	110		3, 4
STANDBY CURRENT (RAS, CAS = ViH)	Standby	l _{CC2}	-	10	-	10		
(100), COS = VIH)	Active	ICCZA	_	50	-	50]	3, 4
RAS ONLY REFRESH CURRENT	Standby	I _{CC3}	-	85	_	70		3, 4
$\left(\frac{\overline{RAS} \text{ Cycling, } \overline{CAS} = V_{IH}}{t_{RC} = t_{RC} \text{ min.}}\right)$	Active	ICC3A	_	125	-	110	mA	3, 4
PAGE MODE CURRENT	Standby	I _{CC4}	-	75	-	60		3, 4
$\left(\overline{RAS} = V_{IL}, \overline{CAS} \text{ Cycling } \right)$ $t_{PC} = t_{PC} \text{ min.}$	Active	ICC4A	-	115	-	100		3, 4
CAS BEFORE RAS REFRESH CURRENT	Standby	l _{CC5}	-	85	-	70		3, 4
$\begin{pmatrix} \overline{RAS} \text{ Cycling, } \overline{CAS} \text{ Before } \overline{RAS} \\ t_{RC} = t_{RC} \text{ min.} \end{pmatrix}$	Active	ICCSA	-	125	-	110		3, 4
DATA TRANSFER CURRENT	Standby	l _{CC6}	-	105	-	90		3, 4
$\left(\frac{\overline{RAS}, \overline{CAS} \text{ Cycling}}{t_{RC} = t_{RC} \text{ min.}}\right)$	Active	I _{CC6A}	-	145	-	130		3, 4

ITEM	SYMBOL	MIN.	MAX.	UNIT	NOTE
INPUT LEAKAGE CURRENT $0V \le V_{IN} \le 6.5V$, All other pins not under test= $0V$	l _{I(L)}	- 10	10	μА	
OUTPUT LEAKAGE CURRENT 0V≤V _{OUT} ≤5.5V, Output Disable	I _{O(L)}	- 10	10	μА	
OUTPUT "H" LEVEL VOLTAGE	VoH	2.4	-	v	
OUTPUT "L" LEVEL VOLTAGE Iout = 2mA	VoL	-	0.4	v	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED A.C. OPERATING CONDITIONS $(V_{CC} = 5V \pm 10\%, Ta = 0 \sim 70^{\circ}C)$ (Notes : 5, 6, 7)

		TC524256	C524256BJ/BZ-80 TC524256BJ/BZ-10		UNIT	NOTE	
SYMBOL	PARAMETER	MIN.	MAX.	MIN.	MAX.	0	1012
tRC	Random Read or Write Cycle Time	150		180			ļ
t _{RMW}	Read - Modify - Write Cycle Time	195		235			<u> </u>
t _{PC}	Fast Page Mode Cycle Time	50		55		ļ	
	Fast Page Mode Read - Modify - Write Cycle	90		100			
LPRMW	Time						<u> </u>
LHAC	Access Time from RAS		80		100	Ì	8,14
TAA	Access Time from Column Address		45		50	Ì	8,14
tCAC	Access Time from CAS		25	<u> </u>	25	-	8,15
tcpa	Access Time from CAS Precharge		45		50	-	8,15
toff	Output Buffer Turn - Off Delay	0	20	0	20	-{	10
tτ	Transition Time (Rise and Fall)	. 3	35	3	35	-	7
tgp	RAS Precharge Time	60		70	ļ	-	
t _{RAS}	RAS Pulse Width	80	10000	100	10000	4	<u> </u>
TRASP	RAS Pulse Width (Fast Page Mode Only)	80	100000	100	100000	4	<u> </u>
t _{RSH}	RAS Hold Time	25		25	<u> </u>	4	
t _{CSH}	CAS Hold Time	80		100		ns	
tCAS	CAS Pulse Width	25	10000	25	10000	_	
t _{RCD}	RAS to CAS Delay Time	20	55	20	75		14
t _{RAD}	RAS to Column Address Delay Time	15	35	15	50	_	14
tRAL	Column Address to RAS Lead Time	45		50		_	
tCRP	CAS to RAS Precharge Time	10		10			<u> </u>
tCPN	CAS Precharge Time	10		10		_	
tce	CAS Precharge Time (Fast Page Mode)	10		10	<u> </u>	_	
TASR	Row Address Set - Up Time	0		0		_	
tRAH	Row Address Hold Time	10		10		_	
tasc	Column Address Set - Up Time	0		0		_	
tcan	Column Address Hold Time	15		15			
tAR	Column Address Hold Time referenced to RAS	55		70	<u> </u>		
t _{RCS}	Read Command Set - Up Time	0	1	0			
tRCH	Read Command Hold Time	0		0		╛	11
tRRH	Read Command Hold Time referenced to RAS	0		0			11
twch	Write Command Hold Time	15		15		╛	
twcr	Write Command Hold Time referenced to RAS	55		70			
LWP	Write Command Pulse Width	15		15		_	
tawi	Write Command to RAS Lead Time	20		25			
tcwL	Write Command to CAS Lead Time	20		25	;		



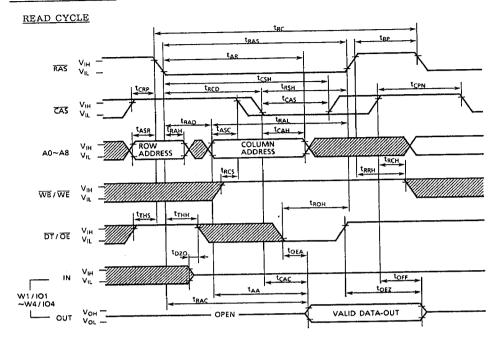
SYMBOL	D.D.L.	TC524256	BJ/BZ-80	TC524256	BJ/8Z-10		
5110300	PARAMETER	MIN.	MAX.	MIN.	MAX.	UNIT	NOT
tos	Data Set-Up Time	0		О		<u> </u>	12
t _{OH}	Data Hold Time	15		15		1	12
tone	Data Hold Time referenced to RAS	55		70		1	
twes	Write Command Set-Up Time	0		0		1	13
tawb	RAS to WE Delay Time	100		130		ns	13
tAWD	Column Address to WE Delay Time	65		80		1	13
towa	CAS to WE Delay Time	45		55		1	13
tozc	Data to CAS Delay Time	0		0			-
^t DZO	Data to OE Delay Time	0		0		Í	
toea	Access Time from OE		20		25	1	8
tosz	Output Buffer Turn - off Delay from OE	0	10	0	20		10
toso	OE to Data Delay Time	10		20			
t _{OEH}	OE Command Hold Time	10		20		İ	-
taon	RAS Hold Time referenced to OE	15		15			_
t _{CSR}	CAS Set - Up Time for CAS Before RAS Cycle	10		10			
t _{CHR}	CAS Hold Time for CAS Before RAS Cycle	10		10			\vdash
tRPC	RAS Precharge to CAS Active Time	0		0	···-		
trer	Refresh Period		8		8	ms	
twsa	W3 Set-Up Time	0		0		,,,,,	
t _{RWH}	W3 Hold Time	15		15			
tus	Write-Per-Bit Mask Data Set-Up Time	0		0			
t _{VH}	Write-Per-Bit Mask Data Hold Time	15		15		Ì	
ttes	DT High Set - Up Time	0		0			
t-pu	DT High Hold Time	15		15			
t _{TLS}	DT Low Set-Up Time	0		0		ŀ	
t _{TLH}	DT Low Hold Time	15	10000	15	10000	ns	
tatu	DT Low Hold Time referenced to RAS	65	10000	80	10000	ŀ	
	(Real Time Read Transfer)		1				
HTA	DT Low Hold Time referenced to Column	30		30		ŀ	
	Address (Real Time Read Transfer)						
СТН	DT Low Hold Time referenced to CAS	25		25		}	
j	(Real Time Read Transfer)				I		

		TC524256	3J / BZ-80	TC524256BJ/BZ-10		UNIT	NOTE
SYMBOL	PARAMETER	MIN.	MAX.	MIN.	MAX.	UNII	NOTE
tesa	SE Set-Up Time referenced to RAS	0		0			
less leen	SE Hold Time referenced to RAS	15		15			
trep	DT to RAS Precharge Time	60		70		1	
tre	DT Precharge Time	20		30			
tRSD	RAS to First SC Delay Time (Read Transfer)	80		100			
tasp	Column Address to First SC Delay Time	45		50			
LASO	(Read Transfer)]	
‡CSD	CAS to First SC Delay Time (Read Transfer)	25		25			
	Last SC to DT Lead Time	5		5	i		
TTSL	(Real Time Read Transfer)]	
tTSD	DT to First SC Delay Time (Read Transfer)	15		15	<u></u>		<u>_</u>
tsas	Last SC to RAS Set - Up Time (Serial Input)	30		30		1	<u></u>
tsrp	RAS to First SC Delay Time (Serial Input)	25		25]	<u></u>
tspp	RAS to Serial Input Delay Time	50		50			<u></u>
	Serial Output Buffer Turn-off Delay from RAS	10	50	10	50		10
tsoz	(Pseudo Write Transfer)	ľ				_	<u></u>
tscc	SC Cycle Time	30		30		ns	
tsc	SC Pulse Width (SC High Time)	10		10]	
tsce	SC Precharge Time (SC Low Time)	10		10	i	_	
1 _{SCA}	Access Time from SC		25		25		9
tson	Serial Output Hold Time from SC	5		5	L	_	
tsos	Serial Input Set - Up Time	0		0		_	_
tsph	Serial Input Hold Time	15		15		_	
tsea	Access Time from SE		25		25	4	9
tse	SE Pulse Width	25		25		1	<u> </u>
TSEP	SE Precharge Time	25		25		_	<u> </u>
tsez	Serial Output Buffer Turn - off Delay from SE	0	20	0	20	_	10
tsze	Serial Input to SE Delay Time	0		0		_	<u> </u>
tszs	Serial Input to First SC Delay Time	0		0		_	<u> </u>
tsws	Serial Write Enable Set-Up Time	0		0		_	_
tswn	Serial Write Enable Hold Time	15		15			-
tswis	Serial Write Disable Set - Up Time	0		0			<u> </u>
tswin	Serial Write Disable Hold Time	15		15			

NOTES:

- Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.
- 2. All voltage are referenced to VSS.
- These parameters depend on cycle rate.
- 4. These parameters depend on output loading. Specified values are obtained with the output open.
- 5. An initial pause of 200µs is required after power-up followed by any 8 RAS cycles (DT/OE "high") and any 8 SC cycles before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS before RAS initialization cycles instead of 8 RAS cycles are required.
- AC measurements assume t_T=5ns.
- VIII (min.) and VIL (max.) are reference levels for measuring timing of input signals. Also, transition times are measured between VIII and VIL.
- 8. RAM port outputs are measured with a load equivalent to 1 TTL load and 100pF. D_{OUT} reference levels : $V_{OII}/V_{OL} = 2.0V/0.8V$.
- SAM port outputs are measured with a load equivalent to 1 TFL load and 30pF.
 D_{OUT} reference levels: V_{OH}/V_{OL}=2.0V/0.8V.
- tOFF (max.), tOEZ (max.), tSDZ (max.) and tSEZ (max.) define the time at which the outputs
 achieve the open circuit condition and are not referenced to output voltage levels.
- 11. Either tRCH or tRRH must be satisfied for a read cycles.
- 12. These parameters are referenced to CAS leading edge of early write cycles and to WB/WE leading edge in OE-controlled-write cycles and read-modify-write cycles.
- 13. twcs, trwd, tcwd and tawd are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twcs≥twcs(min.), the cycle is an early write cycles and the data out pin will remain open circuit (high impedance) throughout the entire cycle; If trwd≥trwd(min.), tcwd≥tcwd(min.) and tawd≥tawd(min.) the cycle is a read-modify-write cycle and the data out will contain data read from the selected cell: If neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 14. Operation within the t_{RCD (max.)} limit insures that t_{RAC (max.)} can be met. t_{RCD (max.)} is specified as a reference point only: If t_{RCD} is greater than the specified t_{RCD (max.)} limit, then access time is controlled by t_{CAC}.
- 15. Operation within the t_{RAD(max.)} limit insures that t_{RAC(max.)} can be met. t_{RAD(max.)} is specified as a reference point only: If t_{RAD} is greater than the specified t_{RAD(max.)} limit, then access time is controlled by t_{AA}.

TIMING WAVEFORM







WRITE CYCLE (EARLY WRITE) t_{RP} tcsH **t**RCD tash t_{CPN} tRAL TASC t_{CAH} ROW COLUMN A0~A8 trwh twcs twch twe WB/WE twcs t_{RWL} DT / OE tos VALID DATA-IN WM1 DATA W1/I01 **t**DHR ~W4/104 - OUT - OPEN -: "H" or "L"

*1 WB/WE	W1/I01~W4/I04	Cycle
0	WM1 data	Write per bit
1	Don't Care	Normal Write

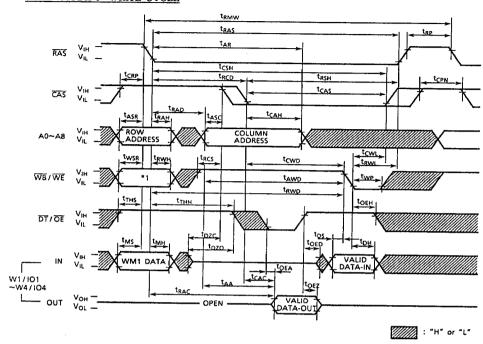
WM1 data: 0: Write Disable 1: Write Enable

WRITE CYCLE (OE CONTROLLED WRITE) tRAS tAR t_{CSH} t_{R5H} t_{RCD} tCAS TRAL 1_{RAD} **ERAH** t_{ASC} tcah ROW COLUMN t_{CWL} twp W8/WE twcr **t**OEH DT/OE t_{DH} VALID DATA-IN WM1 DATA tohr W1/I01 ~W4/I04 V_{ОН} — - OPEN -L___ оит : "H" or "L"

*1 ₩B/₩E	W1/I01~W4/I04	Cycle
0	WM1 data	Write per bit
1	Don't Care	Normal Write

WM1 data: 0 · Write Disable 1 : Write Enable

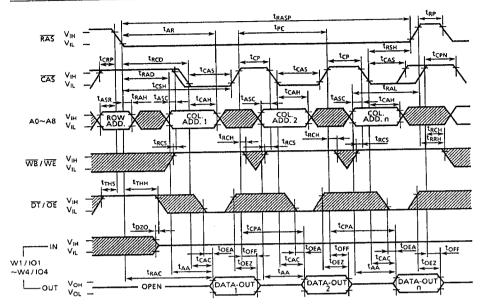
READ - MODIFY - WRITE CYCLE



*1 W8/WE	W1/I01~W4/I04	Cycle
0	WM1 data	Write per bit
1	Don't Care	Normal Write

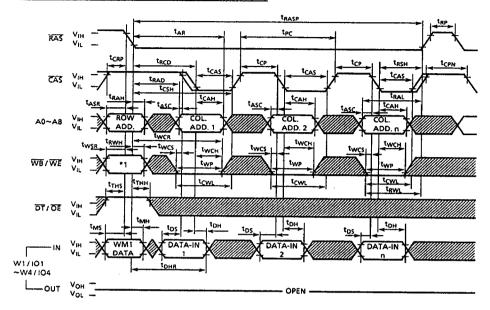
WM1 data: 0: Write Disable 1: Write Enable

FAST PAGE MODE READ CYCLE



: "H" or "L"

FAST PAGE MODE WRITE CYCLE (EARLY WRITE)

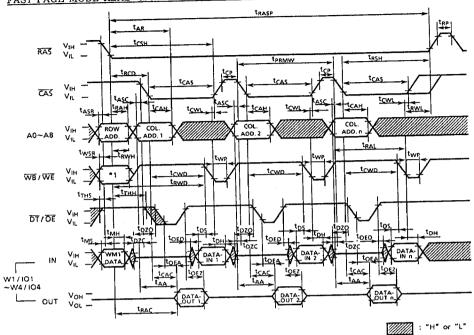


: "H" or "L"

*1 W8/WE	W1/IO1~W4/IO4	Cycle
0	WM1 data	Write per bit
1	Don't Care	Normal Write

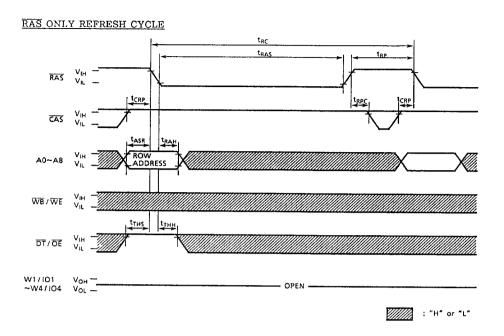
WM1 data: 0: Write Disable 1: Write Enable

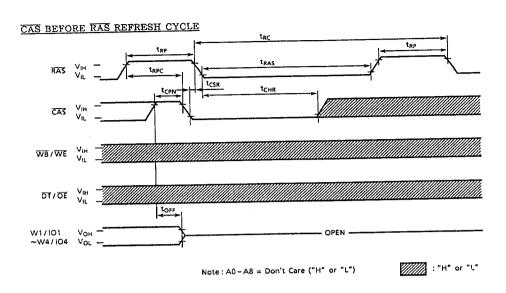
FAST PAGE MODE READ - MODIFY - WRITE CYCLE



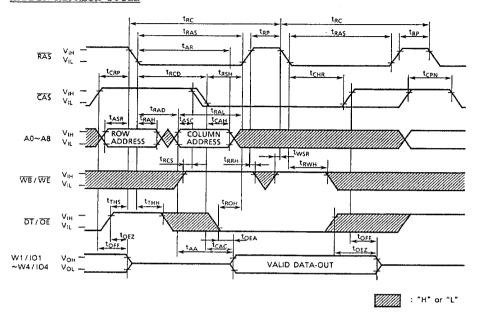
*1 WB/WE	W1/I01~W4/I04	Cycle
0	WM1 data	Write per bit
1	Don't Care	Normal Write

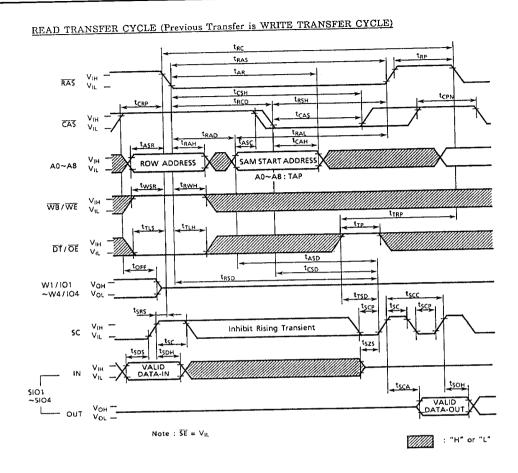
WM1 data: 0: Write Disable 1: Write Enable



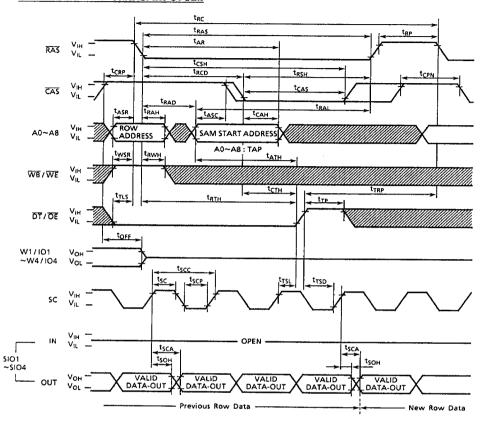


HIDDEN REFRESH CYCLE



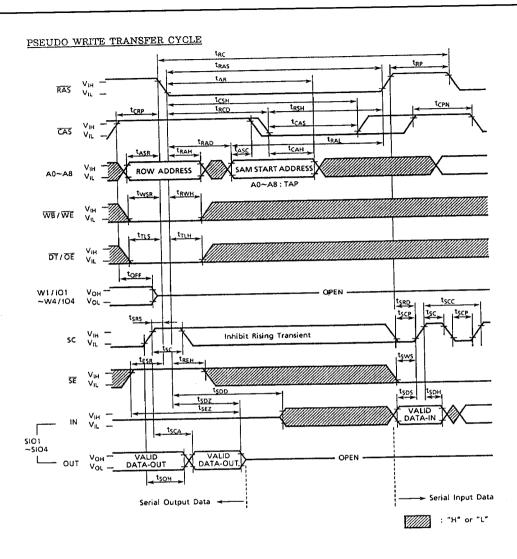


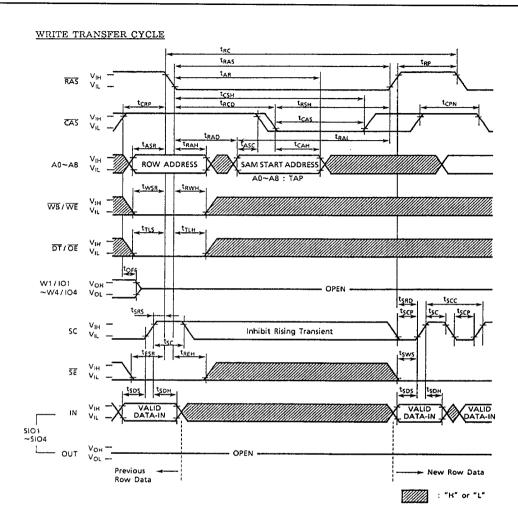
REAL TIME READ TRANSFER CYCLE



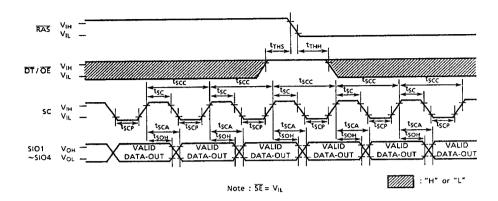
Note : \$E = VIL

: "H" or "L"

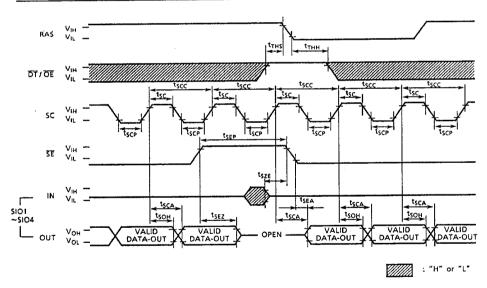




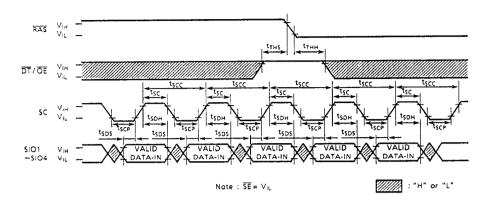
SERIAL READ CYCLE (SE=VIL)



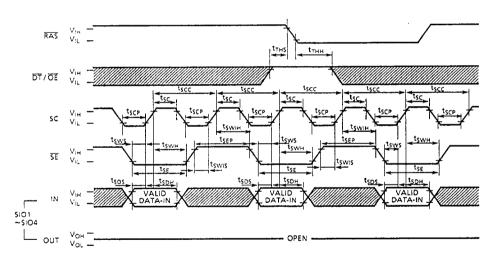
SERIAL READ CYCLE (SE Controlled Outputs)



SERIAL WRITE CYCLE (SE=VIL)



SERIAL WRITE CYCLE (SE Controlled Inputs)



: "H" or "L"

PIN FUNCTION

ADDRESS INPUTS : A0 ~ A8

The 18 address bits required to decode 4 bits of the 1,048,576 cell locations within the dynamic RAM memory array of the TC524256BJ/BZ are multiplexed onto 9 address input pins (A₀~A₈). Nine row address bits are latched on the falling edge of the row address strobe (RAS) and the following nine column address bits are latched on the falling edge of the column address strobe (CAS).

ROW ADDRESS STROBE : RAS

A random access cycle or a data transfer cycle begins at the falling edge of RAS. RAS is the control input that latches the row address bits and the states of CAS, DT/OE, WB/WE and SE to invoke the various random access and data transfer operating modes shown in Table 2.

RAS has minimum and maximum pulse widths and a minimum precharge requirement which must be maintained for proper device operation and data integrity. The RAM port is placed in standby mode when the RAS control is held "high".

COLUMN ADDRESS STROBE : CAS

CAS is the control input that latches the column address bits. CAS has minimum and maximum pulse widths and a minimum precharge requirement which must be maintained for proper device operation and data integrity. CAS also acts as an output enable for the output buffers on the RAM port.

DATA TRANSFER/OUTPUT ENABLE : DT/OE

The $\overline{DT}/\overline{OE}$ input is a multifunction pin. When $\overline{DT}/\overline{OE}$ is "high" at the falling edge of \overline{RAS} , RAM port operations are performed and $\overline{DT}/\overline{OE}$ is used as an output enable control. When the $\overline{DT}/\overline{OE}$ is "low" at the falling edge of \overline{RAS} , a data transfer operation is started between the RAM port and the SAM port.

WRITE PER BIT / WRITE ENABLE : WB / WE

The WB/WE input is also a multifunction pin. When WB/WE is "high" at the falling edge of RAS, during RAM port operations, it is used to write data into the memory array in the same manner as a standard DRAM. When WB/WE is "low" at the falling edge of RAS, during RAM port operations, the write-per-bit function is enabled. The WB/WE input also determines the direction of data transfer between the RAM array and the serial register (SAM).

When $\overline{WB}/\overline{WE}$ is "high" at the falling edge of \overline{RAS} , the data is transferred from RAM to SAM (read transfer). When $\overline{WB}/\overline{WE}$ is "low" at the falling edge of \overline{RAS} , the data is transferred from SAM to RAM (write transfer).



WRITE MASK DATA / DATA INPUT AND OUTPUT: W1/IO1~W4/IO4

When the write-per-bit function is enabled, the mask data on the W_i/IO_i pins is latched into the write mask register (WM1) at the falling edge of \overline{RAS} . Data is written into the DRAM on data lines where the write-mask data is a logic "1". Writing is inhibited on data lines where the write-mask data is a logic "0". The write-mask data is valid for only one cycle. Data is written into the RAM port during a write or read-modify-write cycle. The input data is latched at the falling edge of either \overline{CAS} or $\overline{WB}/\overline{WE}$, whichever occurs late. During an early-write cycle, the outputs are in the high-impedance state. Data is read out of the RAM port during a read or read-modify-write cycle. The output data becomes valid on the W_i/IO_i pins after the specified access times from \overline{RAS} , \overline{CAS} , $\overline{DT}/\overline{OE}$ and column address are satisfied and will remain valid as long as \overline{CAS} and $\overline{DT}/\overline{OE}$ are kept "low". The outputs will return to the high-impedance state at the rising edge of either \overline{CAS} or $\overline{DT}/\overline{OE}$, whichever occurs first.

SERIAL CLOCK: SC

All operations of the SAM port are synchronized with the serial clock SC. Data is shifted in or out of the SAM registers at the rising edge of SC. In a serial read, the output data becomes valid on the SIO pins after the maximum specified serial access time tscA from the rising edge of SC. The serial clock SC also increments the 9-bits serial pointer which is used to select the SAM address. The pointer address is incremented in a wrap-around mode to select sequential locations after the starting location which is determined by the column address in the read transfer cycle. When the pointer reaches the most significant address location (decimal 511), the next SC clock will place it at the least significant address location (decimal 0).

The serial clock SC must be held at a constant $V_{\rm IH}$ or $V_{\rm IL}$ level during read transfer/pseudo write transfer/write transfer operations and should not be clocked while the SAM port is in the standby mode to prevent the SAM pointer from being incremented.

SERIAL ENABLE : SE

The SE input is used to enable serial access operation. In a serial read cycle, SE is used as an output control. In a serial write cycle, SE is used as a write enable control. When SE is "high", serial access is disabled, however, the serial address pointer location is still incremented when SC is clocked even when SE is "high".

SERIAL INPUT/OUTPUT: SIO1~SIO4

Serial input and serial output share common I/O pins. Serial input or output mode is determined by the most recent read, write or pseudo write transfer cycle. When a read transfer cycle is performed, the SAM port is in the output mode. When a write or pseudo write transfer cycle is performed, the SAM port is switched from output mode to input mode. During subsequent write transfer cycle, the SAM remains in the input mode.

OPERATION MODE

The RAM port and data transfer operating of the TC524256BJ/BZ are determined by the state of \overline{CAS} , $\overline{DT}/\overline{OE}$, $\overline{WB}/\overline{WE}$ and \overline{SE} at the falling edge of \overline{RAS} . The Table 1 and the Table 2 show the operation truth table and the functional truth table for a listing of all available RAM port and transfer operation, respectively.

Table 1. Operation Truth Table	Table	1	Operation	Truth	Table
--------------------------------	-------	---	-----------	-------	-------

Function	RAS falling edge						
Tuncaon	ŠĒ	WB/WE	DT/OE	TAS			
CAS before RAS Refresh	*	*	*	0			
Write Transfer	0	0	0	1			
Pseudo Write Transfer	1	0	0	1			
Read Transfer	*	1	0	1			
Read/Write per Bit	*	0	1	1			
Read / Write	*	1	1	1			

Table 2. Functional Truth Table

		ŘΑ	3 7		Ad	dress	w	/10	Write Mask
Function	CAS	DT/OE	WB/WE	SE	. RAS TL	CAS TL	RAS TL	CAS TL	WM1
CAS before RAS Refresh	0	*	*	*	*		*	-	_
Write Transfer	1	0	0	0	Row	TAP	*	•	-
Pseudo Write Transfer	1	0	0	1	Row	TAP		*	-
Read Transfer	1	0	1	*	Row	TAP	•	*	
Write per Bit	1	1	0	*	Row	Column	WM1	DIN	Load use
Read / Write	1	1	1	•	Row	Column	*	DIN	-

*: "0" or "1" , TAP: SAM start address , -: not used

RAM PORT OPERATION

FAST PAGE MODE CYCLE

Fast page mode allows data to be transferred into or out of multiple column locations of the same row by performing multiple $\overline{\text{CAS}}$ cycle during a single active $\overline{\text{RAS}}$ cycle. During a fast page cycle, the $\overline{\text{RAS}}$ signal may be maintained active for a period up to 100 pseconds. For the initial fast page mode access, the output data is valid after the specified access times from $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, column address and $\overline{\text{DT}}/\overline{\text{OE}}$. For all subsequent fast page mode read operations, the output data is valid after the specified access times from $\overline{\text{CAS}}$, column address and $\overline{\text{DT}}/\overline{\text{OE}}$. When the write-per-bit function is enabled, the mask data latched at the falling edge of $\overline{\text{RAS}}$ is maintained throughout the fast page mode write or read-modify-write cycle.

RAS-ONLY REFRESH

The data in the DRAM requires periodic refreshing to prevent data loss. Refreshing is accomplished by performing a memory cycle at each of the 512 rows in the DRAM array within the specified 8ms refresh period. Although any normal memory cycle will perform the refresh operation, this function is most easily accomplished with "RAS-Only" cycle.

CAS-BEFORE-RAS REFRESH

The TC524256BJ/BZ also offers an internal-refresh function. When CAS is held "low" for a specified period (tcsr) before RAS goes "low", an internal refresh address counter and on-chip refresh control clock generators are enabled and an internal refresh operation takes place. When the refresh operation is completed, the internal refresh address counter is automatically incremented in preparation for the next CAS-before-RAS cycle. For successive CAS-before-RAS refresh cycle, CAS can remain "low" while cycling RAS.

HIDDEN REFRESH

A hidden refresh is a CAS-before-RAS refresh performed by holding CAS "low" from a previous read cycle. This allows for the output data from the previous memory cycle to remain valid while performing a refresh. The internal refresh address counter provides the address and the refresh is accomplished by cycling RAS after the specified RAS-precharge period (Refer to Figure 1).

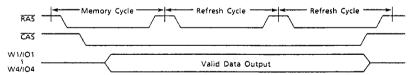


Figure 1. Hidden Refresh Cycle

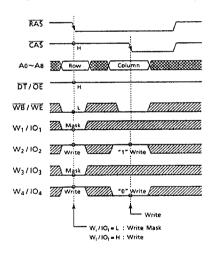
WRITE-PER-BIT FUNCTION

The write-per-bit function selectively controls the internal write-enable circuits of the RAM port. When \overline{Wii}/WE is held "low" at the falling edge of \overline{ILAS} , during a random access operation, the write-mask is enabled. At the same time, the mask data on the W_i/IO_i pins is latched onto the write-mask register (WM1). When a "0" is sensed on any of the W_i/IO_i pins, their corresponding write circuits are disabled and new data will not be written. When a "1" is sensed on any of the W_i/IO_i pins, their corresponding write circuits will remain enabled so that new data is written. The truth table of the write-per-bit function is shown in Table 3.

1 a	Table 3. Truth table for write-per-bit function								
	At the fa	Function							
C AS	DT/OE	WB/WE	W _i /10 _i (i = 1~4)	Tuncaon					
н	н	н	•	Write Enable					
			1	Write Enable					
н	н	"	0	Write Mask					

Table 3. Truth table for write-per-bit function

An example of the write-per-bit function illustrating its application to displays is shown in Figures 2 and 3.



CRT Display

CRT D

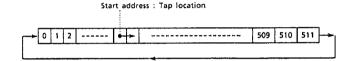
Figure 2. Write-per-bit timing cycle

Figure 3. Corresponding bit-map

SAM PORT OPERATION

The TC524256BJ/BZ is provided with a 512 words by 4 bits serial access memory (SAM). High speed serial read or write operations can be performed through the SAM port independent of the RAM port operations, except during read transfer/write transfer/pseudo-write transfer cycles. The preceding transfer operation determines the direction of data flow through the SAM port. If the preceding transfer operation is a read transfer, the SAM port is in the output mode. If the preceding transfer operation is a write or pseudo write transfer, the SAM port is in the input mode. The pseudo write transfer operation only switches the SAM port from output mode to input mode; Data is not transferred from SAM to RAM.

Serial data can be read out of the SAM port after a read transfer (RAM-SAM) has been performed. The data is shifted out of the SAM port starting at any of the 512 bits locations. The TAP location corresponds to the column address selected at the falling edge of CAS during the read transfer cycle. The SAM registers are configured as circular data registers. The data is shifted out sequentially starting from the selected tap location to the most significant bit and then wraps around to the least significant bit, as illustrated below.



Subsequent real-time read transfer may be performed on-the-fly as many times as desired, within the refresh constraints of the DRAM array. Simultaneous serial read operation can be performed with some timing restrictions. A pseudo write transfer cycle is performed to change the SAM port from output mode to input mode in order to write data into the serial registers through the SAM port. A write transfer cycle must be used subsequently to load the SAM data into the RAM row selected by the row address at the falling edge of \overline{RAS} . The starting location in the SAM registers for the next serial write is selected by the column address at the falling edge of \overline{CAS} . The truth table for single register mode SAM operation is shown in Table 4.

Table 4. Truth Table for SAM Port Operation

SAM PORT OPERATION	DT/OE at the failing edge of RAS	sc	SE	FUNCTION	Preceded by a		
		<u></u>	L	Enable Serial Read	Read Transfer		
Serial Output Mode	Ì	- -	Н	Disable Serial Read	Read Transfer		
	1		L	Enable Serial Write	Write Transfer		
Serial Input Mode	н		н	Disable Serial Write			
		-			L	Enable Serial Write	
Serial Input Mode			н	Disable Serial Write	Pseudo Write Transfer		

REFRESH

The SAM data registers are static flip-flop, therefore a refresh is not required.

DATA TRANSFER OPERATION

The TC524256BJ/BZ features the internal bidirectional data transfer capability between RAM and the SAM, as shown in Figure 4. During a transfer, 512 words by 4 bits of data can be loaded from RAM to SAM (Read Transfer) or from SAM to RAM (Write Transfer).

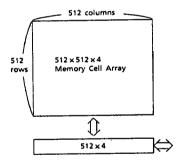


Figure 4. Data Transfer

As shown in Table 5, the TC524256BJ/BZ supports three types of transfer operations: Read transfer, Write transfer and Pseudo write transfer. Data transfer operations between RAM and SAM are invoked by holding the $\overline{DT}/\overline{OE}$ signal "low" at the falling edge of \overline{RAS} . The type of data transfer operation is determined by the state of \overline{CAS} , $\overline{WB}/\overline{WE}$ and \overline{SE} latched at the falling edge of \overline{RAS} . During data transfer operations, the SAM port is switched from input to output mode (Read transfer) or output to input mode (Write transfer/Pseudo write transfer). During a data transfer cycle, the row address $A_0 \sim A_8$ select one of the 512 rows of the memory array to or from which data will be transferred and the column address $A_0 \sim A_8$ select one of the tap locations in the serial register. The selected tap location is the start position in the SAM port from which the first serial data will be read out during the subsequent serial read cycle or the start position in the SAM port into which the first serial data will be written during the subsequent serial write cycle.

at th	at the falling edge of RAS								
CAS	DT/OE	WB/WE	SE	Transfer Mode	Transfer Direction	Transfer 8it	SAM Port Mode		
Н	Ļ	н	*	Read Transfer	RAM → SAM	512×4	Input → Output		
н	L	L	L	Write Transfer	SAM → RAM	512×4	Output → Input		
н	L	Ļ	н	Pseudo Write Transfer	_	_	Output → Input		

Table 5. Transfer Modes

• : "II" or "l."

READ TRANSFER CYCLE

A read transfer consists of loading a selected row of data from the RAM array into the SAM register. A read transfer is invoked by holding CAS "high", DT/OE "low" and WB/WE "high" at the falling edge of RAS. The row address selected at the falling edge of RAS determines the RAM row to be transferred into the SAM. The transfer cycle is completed at the rising edge of DT/OE. When the transfer is completed, the SAM port is set into the output mode.

In a read/real time read transfer cycle, the transfer of a new row of data is completed at the rising edge of $\overline{DT}/\overline{OE}$ and this data becomes valid on the SIO lines after the specified access time t_{SCA} from the rising edge of the subsequent serial clock (SC) cycle. The start address of the serial pointer of the SAM is determined by the column address selected at the falling edge of \overline{CAS} .

Figure 5 shows the operation block diagram for read transfer operation.

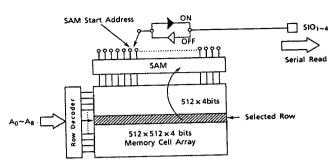


Figure 5. Block Diagram for Read Transfer Operation

In a read transfer cycle (which is preceded by a write transfer cycle), the SC clock must be held at a constant V_{IL} or V_{IH} , after the SC high time has been satisfied. A rising edge of the SC clock must not occur until after the specified delay t_{TSD} from the rising edge of $\overline{DT}/\overline{OE}$, as shown in Figure 6.

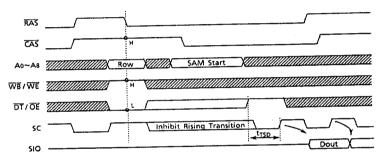


Figure 6. Read Transfer Timing

In a real time read transfer cycle (which is preceded by another read transfer cycle), the previous row data appears on the SIO lines until the $\overline{DT}/\overline{OE}$ signal goes "high" and the serial access time t_{SCA} for the following serial clock is satisfied. This feature allows for the first bit of the new row of data to appear on the serial output as soon as the last bit of the previous row has been strobed without any timing loss. To make this continuous data flow possible, the rising edge of $\overline{DT}/\overline{OE}$ must be synchronized with \overline{RAS} , \overline{CAS} and the subsequent rising edge of SC (trth, toth, and trsl/trsD must be satisfied), as shown in Figure 7.

The timing restriction trst/trsp are 5ns min/15ns min.

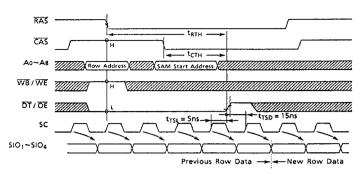


Figure 7. Real Time Read Transfer

WRITE TRANSFER CYCLE

A write transfer cycle consist of loading the content of the SAM register into a selected row of the RAM array. If the SAM data to be transferred must first be loaded through the SAM port, a pseudo write transfer operation must precede the write transfer cycles. However, if the SAM port data to be transferred into the RAM was previously loaded into the SAM via a read transfer, the SAM to RAM transfer can be executed simply by performing a write transfer directly. A write transfer is invoked by holding \overline{CAS} "high", $\overline{DT}/\overline{OE}$ "low", $\overline{WB}/\overline{WE}$ "low" and \overline{SE} "low" at the falling edge of \overline{RAS} .

Figure 8 and 9 show the timing diagram and block diagram for write transfer operations, respectively.

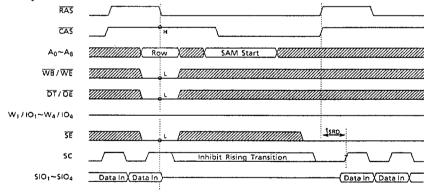


Figure 8. Write Transfer Timing

The row address selected at the falling edge of RAS determines the RAM row address into which the data will be transferred. The column address selected at the falling edge of CAS determines the start address of the serial pointer of the SAM. After the write transfer is completed, the SIO lines are set in the input mode so that serial data synchronized with the SC clock can be loaded.

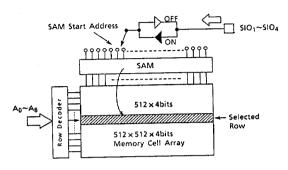


Figure 9. Block Diagram for Write Transfer Operation

When consecutive write transfer operations are performed, new data must not be written into the serial register until the \overline{RAS} cycle of the preceding write transfer is completed. Consequently, the SC clock must be held at a constant V_{IL} or V_{IH} during the \overline{RAS} cycle. A rising edge of the SC clock is only allowed after the specified delay t_{SRD} from the rising edge of \overline{RAS} , at which time a new row of data can be written in the serial register.

PSEUDO WRITE TRANSFER CYCLE

A pseudo write transfer cycle must be performed before loading data into the serial register after a read transfer operation has been executed. The only purpose of a pseudo write transfer is to change the SAM port mode from output mode to input mode (A data transfer from SAM to RAM does not occur). After the serial register is loaded with new data, a write transfer cycle must be performed to transfer the data from SAM to RAM. A pseudo write transfer is invoked by holding CAS "high", DT/OE "low", WB/WE "low" and SE "high" at the falling edge of RAS. The timing conditions are the same as the one for the write transfer cycle except for the state of SE at the falling edge of RAS.



REGISTER OPERATION SEQUENCE (EXAMPLE)

Figure 10 illustrates an example of register operation sequence after device power-up and initialization. After power-up, a minimum of 8 RAS and 8 SC clock cycles must be performed to properly initialize the device. A read transfer is then performed and the column address latched at the falling edge of CAS sets the SAM tap pointer location which up to that point was in an undefined location. Subsequently, the pointer address is incremented by cycling the serial clock SC from the starting location to the last location in the register (address 511) and wraps around to the least significant address location. The SAM address is incremented as long as SC is clocked.

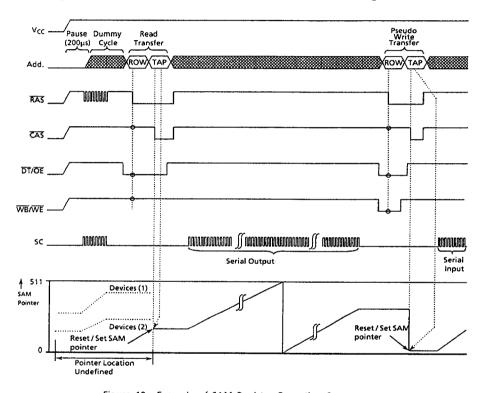
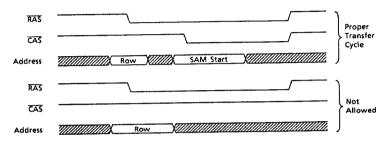


Figure 10. Example of SAM Register Operation Seguence

The next operation is a pseudo write transfer which switches the SAM port from output mode to input mode in preparation for write transfers. The column address latched at the falling edge of CAS during the pseudo write transfer sets the serial register tap location. Serial data will be written into the SAM starting from this location.

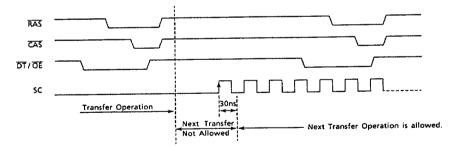
TRANSFER OPERATION WITHOUT CAS

During all transfer cycles, the \overline{CAS} input clock must be cycled, so that the column address are latched at the falling edge of \overline{CAS} , to set the SAM tap location. If \overline{CAS} was maintained at a constant "high" level during a transfer cycle, the SAM pointer location would be undefined. Therefore a transfer cycle with \overline{CAS} held "high" is not allowed (Refer to the illustration below).



READ TRANSFER CYCLE AFTER READ TRANSFER CYCLE

Another read transfer may be performed following the read transfer provided that a minimum delay of 30ns from the rising edge of the first clock SC is satisfied (Refer to the illustration shown below).



POWER-UP

Power must be applied to the \overline{RAS} and $\overline{DT}/\overline{OE}$ input signals to pull them "high" before or at the same time as the VCC supply is turned on. After power-up, a pause of 200 pseconds minimum is required with \overline{RAS} and $\overline{DT}/\overline{OE}$ held "high". After the pause, a minimum of 8 \overline{RAS} and 8 SC dummy cycles must be performed to stabilize the internal circuitry, before valid read, write or transfer operations can begin. During the initialization period, the $\overline{DT}/\overline{OE}$ signal must be held "high". If the internal refresh counter is used, a minimum 8 \overline{CAS} -before- \overline{RAS} initialization cycles are required instead of 8 \overline{RAS} cycles.

INITIAL STATE AFTER POWER-UP

When power is achieved with RAS, CAS, DT/OE and WB/WE held "high", the internal state of the TC524256BJ/BZ is automatically set as follows.

However, the initial state can not be guaranteed for various power-up conditions and input signal levels. Therefore, it is recommended that the initial state be set after the initialization of the device is performed (200 pseconds pause followed by a minimum of 8 RAS cycles and 8 SC cycles) and before valid operations begin.

	State after power-up
SAM port	Input Mode
WM1 Register	Write Enable
TAP pointer	Invalid